HYPREZ® WAFER PROCESSING PILOT PRODUCTION AND R&D SYSTEMS FOR GRINDING, LAPPING & POLISHING

ADVANCED MATERIALS PRODUCTS

6" HORIZONTAL WAFER GRINDER

6" Horizontal Wafer Grinder

Repeatable Results with High-Yield Features:

- Precision depth control
- TTV to <1µ
- 2 or 3 axis motion
- Spindle oscillation reduces surface damage
- Reduces lapping & polishing cycles

Attractive Cost of Ownership:

- Affordable initial pricing
- Compact footprint
- Durable design reduces maintenance
- Low electrical consumption

15" Lapping/Polishing System Featuring Plate Preparation

System Features On-Board Flatness, Texturing & Contour Control System:

- Micro-textures plates for primary & secondary lapping, epitaxial polishing
- Flatness control within 2 microns
- Micro-texturing eliminates the need to pad polish most materials
- Also effective for planarization pad conditioning and grooving
- Temperature & contamination control available for clean-room use
- Available for 12" - 48" plate diameters

15" LAPPING/POLISHING SYSTEM

MPC FOR POLISHING & PLANARIZING

18" Maximum Process Control (MPC) For Polishing & Planarizing

6-Sigma Capability for Material Removal, Flatness & Surface Finish Generation:

- Menu-driven, computer control allows any lap or polish process to be fully optimized
- Superior device flatness & finish
- Extended plate flatness & texture
- Oscillation system provides 3-axis motion for true CMP kinematics
- Computer-controlled, independent 3 spindle operation
- Enhanced polishing pad life & performance

FOR ADDITIONAL INFORMATION CONTACT THE ENGIS MICROTECH TEAM AT

WWW.ENGISCA.COM

MICROFINISHING TECHNOLOGY CENTER

Engis Corporation proudly offers our customers the use of our newly established Microfinishing Technology Center.

The experienced staff in our technology center is your resource to:

- Solve difficult application problems
- Attain the tightest finish and flatness tolerances
- Improve your production throughput
- Maximize yield
- Develop the most robust and efficient process

Our MTC is outfitted with the latest diamond processing equipment to take you from rough grinding through final CMP-D polish, including advanced metrology to document the results. Whether you are planarizing a multi-material MEMS wafer or targeting an epi-finish on semiconductor substrates, our expert staff can assist you in meeting and exceeding your goals.

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